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(54) Title (EN): CONDUCTIVE ADHESIVE FILM HAVING EXCELLENT HEAT RESISTANCE AND MOISTURE RESISTANCE

(54) Title (FR): FILM ADHÉSIF CONDUCTEUR PRÉSENTANT UNE REMARQUABLE RÉSISTANCE À LA CHALEUR ET UNE REMARQUABLE RÉSISTANCE À L'HUMIDITÉ

(54) Title (KO): 내열성 및 내습성이 우수한 전도성 접착 필름

(57) Abstract:

(EN): The present invention relates to a conductive adhesive film having excellent heat resistance and moisture resistance, and has an adhesive layer, which is made of a conductive adhesive composition comprising 100 parts by weight of a polyamide resin represented by chemical formula 1, 100-400 parts by weight of a conductive metal and 0.1-5 parts by weight of a siloxane compound, and is layered on the surface of a substrate, thereby improving the heat resistance of an adhesive film, facilitates curing with the siloxane compound, thereby improving moisture resistance, and has improved long-term reliability of the heat resistance and moisture resistance.

(FR): La présente invention concerne un film adhésif conducteur présentant une remarquable résistance à la chaleur et une remarquable résistance à l'humidité, et possédant une couche adhésive, qui est constituée d'une composition adhésive conductrice comprenant 100 parties en poids d'une résine de polyamide représentée par la formule chimique 1, 100 à 400 parties en poids d'un métal conducteur et 0,1 à 5 parties en poids d'un composé siloxane, et dont une couche est déposée sur la surface d'un substrat, ce qui permet d'améliorer la résistance à la chaleur d'un film adhésif, facilite le durcissement grâce au composé siloxane, améliorant ainsi la résistance à l'humidité. La fiabilité à long terme de la résistance à la chaleur et de la résistance à l'humidité est, en outre, améliorée.

(KO): 본 발명은 내열성 및 내습성이 우수한 전도성 접착 필름으로서, 화학식 1로 표시되는 폴리아미드 수지 100 중량부; 전도성 금속 100 내지 400 중량부; 실록산 화합물 0.1 내지 5 중량부;를 포함하는 전도성 접착제 조성물로 이루어진 접착층이 기재의 표면에 적층되어 접착 필름의 내열성을 향상시키며 실록산 화합물과의 경화 작용이 용이하여 내습성이 향상되되 상기 내열성 및 내습성에 대한 장기 신뢰성이 향상된 접착 필름에 관한 것이다.

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